

### Claims

1. A method of manufacture of an electronic assembly (8), the  
5 electronic assembly (8) comprising a circuit board and an electrical  
component (10), the method comprising the steps of:

laying a first terminal of the electrical component (10) upon a  
conductive region (12) of the circuit board, and providing solder paste (16)  
contacting the first terminal of the component (10) and the circuit board;

10 the method being characterised by the steps of: heating the solder  
paste (16) so as to liquefy the solder paste (16); thereby permitting a  
second terminal (18) of the component (10) to rise above the first terminal  
so as to erect the component (10) substantially perpendicular to the  
conductive region (12);

15 curing the liquefied solder paste (16) in order to fix the first terminal  
of the component (10) to the conductive region (12) of the circuit board.

2. A method according to Claim 1 further comprising the step of:  
electrically connecting the second terminal (18) of the component  
20 (10) to a first terminal of an electrical device (24).

3. A method as claimed in any one of the preceding claims, wherein  
the second terminal (18) of the component (10) is gold plated.

25 4. A method as claimed in Claim 2 or Claim 3, wherein the electronic  
device (24) is an integrated circuit.

5. A method as claimed in Claim 2 or Claim 3, wherein the electronic  
device (24) is an electrical component.

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6. An electronic assembly (8) comprising a conductive region (12), and an electrical component (10) having a first terminal at a first end and a second terminal (18) at a second end, the first terminal being fixed to the conductive region (12) and the second terminal (12) being disposed  
5 substantially perpendicular to the conductive region;

characterised in that:

- the second terminal (12) is arranged to receive connecting means (20) for facilitating an electrical connection between the component (10) and an electronic device (24).  
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7. An electronic assembly (8) as claimed in Claim 6, wherein the second terminal (18) of the component (10) is gold plated.

8. An electronic assembly (8) as claimed in Claim 6 or Claim 7,  
15 wherein the connecting means (20) is a wire bond.

9. An electronic assembly (8) as claimed in any one of the claims 6 to 8, wherein the electronic device (24) is an integrated circuit or an electrical component.  
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10. A use of tombstoning in a method of manufacture of an electronic assembly (8).